Hybrid 8j276 Traveler

March 3, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J276 has die: 182-118 182-119 182-120 182-122 182-092 182-094 182-095 182-096

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 8j276 classification info. Created 10:22:21 03/03/00

Hybrid 8j276 quality: fair
Chip classification: good fair good fair good good fair good
Bad channels (chip-channel): 1-20
Bad cells: none
Random bad capacitors (chip-cell-channel): 3-21-32 3-34-32 3-34-33
   3-35-32 3-38-32 3-38-33 3-39-32 3-41-32 3-41-33 3-43-32 3-43-33
   3-45-32 3-45-33 3-8-31 3-8-32 3-8-33 3-9-32 6-43-61
Channels at pedestal needed for DCMS: 32.7 35.3 37.2 34.6 32.6 33.6 35.6 35.2
```

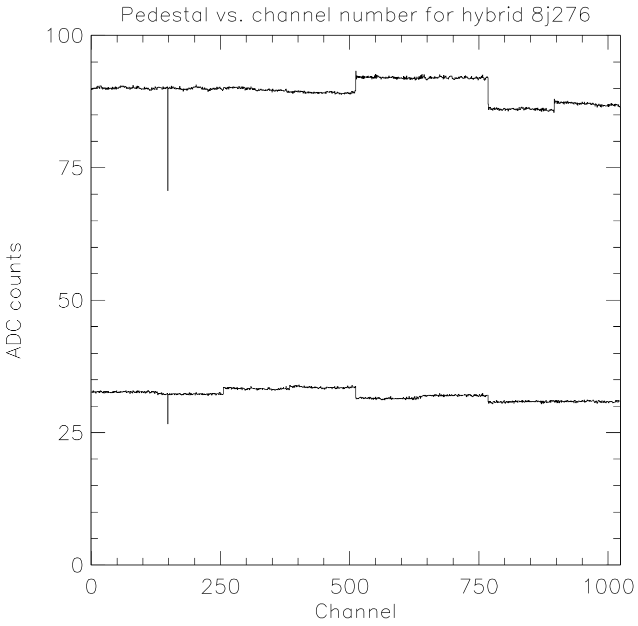
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

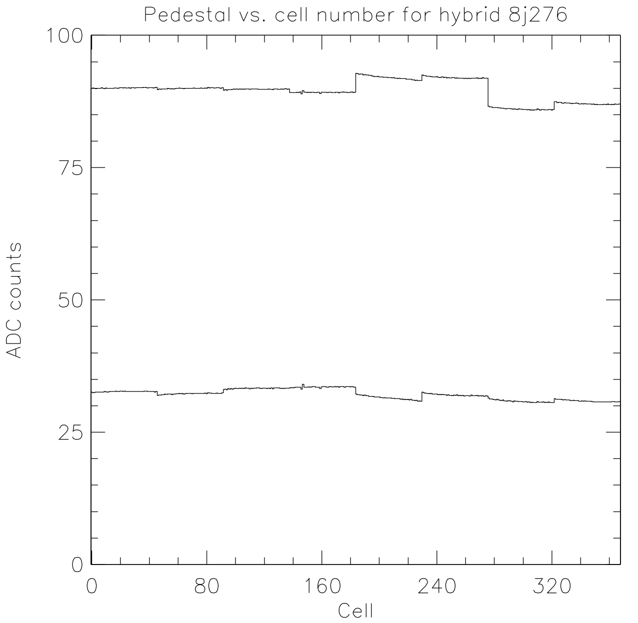
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

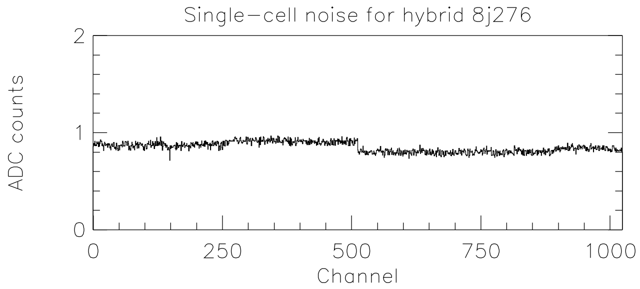
Pedestal vs. Pipeline Cell ID



6 Noise

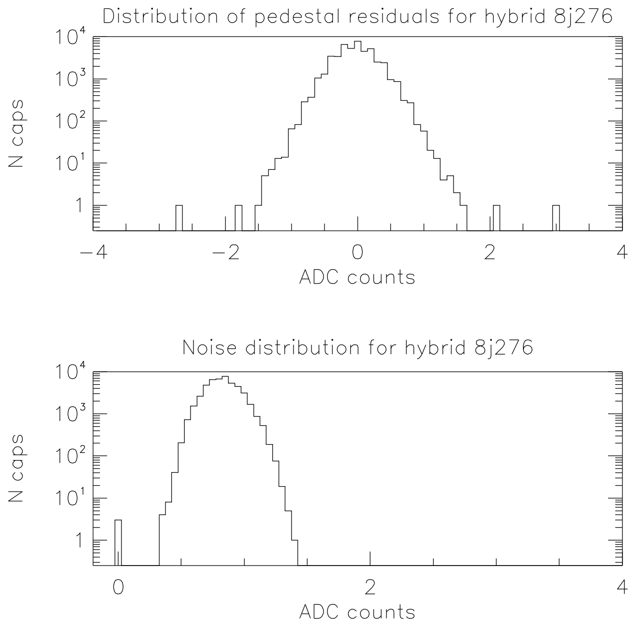
The following plots show the single-cell and multi-cell RMS noise:

RMS Noise



The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise



7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in